

X2DFNW2 1.0x0.6, **0.65P**CASE 711BG ISSUE C

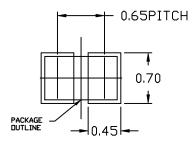
DATE 13 SEP 2019

NOTES:

-D1

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 FROM THE TERMINAL TIP.

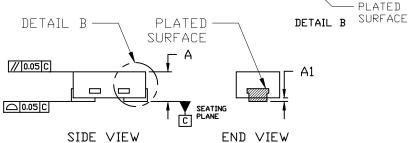
	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	0.34	0.37	0.40
A1			0.05
b	0.45	0.50	0.55
D	0.90	1.00	1.10
D1			0.05
E	0.50	0.60	0.70
e	0.65 BSC		
L	0.22 REF		
L1	0.24	0.285	0.34

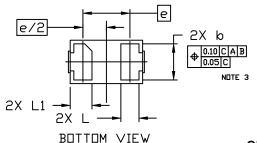


RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering detalls, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

2X 0.05 C PIN 1 REFERENCE TOP VIEW





GENERIC MARKING DIAGRAM*



XX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	X2DFNW2 1.0X0.6, 0.65P		PAGE 1 OF 1	

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